

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JINN-YEH CHIEN	12/13/2013
YUNG-CHOW PENG	06/20/2014
CHUNG-CHIEH YANG	12/13/2013
KUAN-YU LIN	12/24/2013
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	NO. 8, LI-HSIN RD. 6
Internal Address:	HSIN-CHU SCIENCE PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14134259
CORRESPONDENCE DATA	
Fax Number:	(216)502-0601
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	216-502-0600
Email:	docketing@eschweilerlaw.com
Correspondent Name:	ESCHWEILER & ASSOCIATES, LLC.
Address Line 1:	629 EUCLID AVENUE, SUITE 1000
Address Line 2:	NATIONAL CITY BANK BUILDING
Address Line 4:	CLEVELAND, OHIO 44114
ATTORNEY DOCKET NUMBER:	TSMCP378US
NAME OF SUBMITTER:	DAVID W. POTASHNIK
SIGNATURE:	/David W. Potashnik/
DATE SIGNED:	07/02/2014
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TSMC Docket No. TSMC2013-1588

U.S. Patent Appln. No.

Docket No. TSMCP378US

Filing Date

PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT

Assignor(s):

Jinn-Yeh Chien
No. 107, Hsin Shi St.
Hsin Chu
Chu Bei City
Taiwan (R.O.C.)

Assignor(s):

Yung-Chow Peng
10F-3, No. 211, Guan-Hsin Rd.
Hsinchu
Taiwan (R.O.C.)

Assignor(s):

Chung-Chieh Yang
5F, No. 20, Chenggong 3rd Rd.
Hsinchu County
Zhubei City 302
Taiwan (R.O.C.)

Assignor(s):

Kuan-Yu Lin
No. 3, Ln. 6, Wufeng 1st Rd.
Zhudong Township
Hsinchu County 310
Taiwan (R.O.C.)

Assignee:

Taiwan Semiconductor Manufacturing Co., Ltd.
No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park
Hsin-Chu, Taiwan 300-77
Republic of China

AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled

"IN SITU ON THE FLY ON-CHIP VARIATION MEASUREMENT" for which:

a non-provisional application for United States Letters Patent:

PATENT

REEL: 033228 FRAME: 0776

TSMC Docket No. TSMC2013-1588

U.S. Patent Appl. No.

Docket No. TSMCP378US

Filing Date

☒ was executed on even date preparatory to filing (each inventor should sign this Assignment on the same day as he/she signs the Declaration and Power of Attorney); or

☐ was filed on _____ and accorded U.S. Serial No. _____; or

☐ I hereby authorize and request my attorney associated with Customer No. 107476, to insert on the designated lines below the filing date and application number of said application when known:

U.S. Serial No. _____,

filed on _____.

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors

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TSMC Docket No. TSMC2013-1588

Docket No. TSMCP378US

and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

2013/12/13
Date

Jinn-Yeh Chien
Name 1st Inventor Jinn-Yeh Chien

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TSMC Docket No. TSMC2013-1588

Docket No. TSMCP378US

06/20, 2014
Date

Yung-Chow Peng
Name 2nd Inventor Yung-Chow Peng

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2013.12.13

Date

Yang, Chung-Chieh
Name 3rd Inventor Chung-Chieh Yang

TSMC Docket No. TSMC2013-1588

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Docket No. TSMCP378US

Filing Date

2013.12.24

Date

Kuan-Yu Lin

Name 4th Inventor Kuan-Yu Lin